

WHAT IS CLAIMED IS:

*Sub A2*  
1. An electronic part, wherein a coating containing resin ingredient is provided on the surface of an external electrode thereof.

*B*  
2. The electronic part as set forth in claim 1, wherein a conductive adhesive layer is provided on said coating and said conductive adhesive layer contains a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

3. The electronic part as set forth in claim 1, wherein said coating contains a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

*Sub B2*  
4. The electronic part as set forth in claim 2, wherein the thickness of said coating is less than the particle diameter of said conductive filler.

5. An electronic part having a external electrode comprising a coating of a conductive adhesive, wherein said conductive adhesive contains a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

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6. An electronic part mounting element comprising:  
an electronic part;  
a coating containing a resin ingredient and formed on a surface  
of an external electrode of said electronic part;  
an element to be mounted with said electronic part; and  
a conductive adhesive containing a conductive filler  
consisting of gold, silver, platinum, nickel, zinc, palladium,  
or an alloy or a mixture containing these metals and electrically  
connecting the external electrode of said electronic part to a  
connecting terminal of said element to be mounted.

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7. An electronic part mounting element as set forth in claim  
6, wherein said coating and said conductive adhesive are combined  
into one element.

8. The electronic part mounting element as set forth in claim  
7, wherein a joining portion of said coating with said conductive  
adhesive is shaped like a fillet.

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9. An electronic part mounting element, wherein a coating of  
a conductive adhesive containing a conductive filler consisting  
of gold, silver, platinum, nickel, zinc, palladium, or an alloy  
or a mixture containing these metals is formed on the surface of  
the external electrode of the electronic part and said external

electrode of said electronic part is electrically connected to the connecting terminal of an element to be mounted, utilizing said coating as a connecting element.

10. A process of manufacturing an electronic part mounting element, wherein after a coating containing resin ingredient is formed on the surface of an external electrode of an electronic part, said external electrode of said electronic part is electrically connected to a connecting terminal of an element to be mounted by using a conductive adhesive containing a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

11. A process of manufacturing an electronic part mounting element, wherein after a coating of a conductive adhesive containing a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals is formed on a surface of an external electrode of an electronic part, said external electrode of said electronic part is electrically connected to a connecting terminal of an element to be mounted, utilizing said coating as a connecting element.

12. The process of manufacturing an electronic part mounting

element as set forth in claim 11, wherein after said coating is formed on a surface of an electronic part in a half-cured condition, said coating is thermally cured in connecting said electronic part to an element to be mounted.

13. An electronic part, wherein surface roughness ( $R_a$ ) of an external electrode of an electronic part is set to 0.1  $\mu\text{m}$  or more and to 10.0  $\mu\text{m}$  or less.

14. An electronic part as set forth in claim 13, said surface roughness ( $R_a$ ) is set to 1.0  $\mu\text{m}$  or more and to 5.0  $\mu\text{m}$  or less.

15. An electronic part as set forth in claim 13, wherein at least a surface portion of said external electrode is composed of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

16. An electronic part mounting element comprising:  
an electronic part;  
an element to be mounted mounted with said electronic part;  
and  
a conductive adhesive electrically connecting the external electrode of said electronic part to a connecting terminal of said element to be mounted;  
wherein surface roughness ( $R_a$ ) of said external electrode is set

to 0.1  $\mu\text{m}$  or more and to 10.0  $\mu\text{m}$  or less.

17. An electronic part mounting element as set forth in claim 16, wherein said surface roughness ( $R_a$ ) is set to 1.0  $\mu\text{m}$  or more and to 5.0  $\mu\text{m}$  or less.

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*A 5*